

FIG. 1A

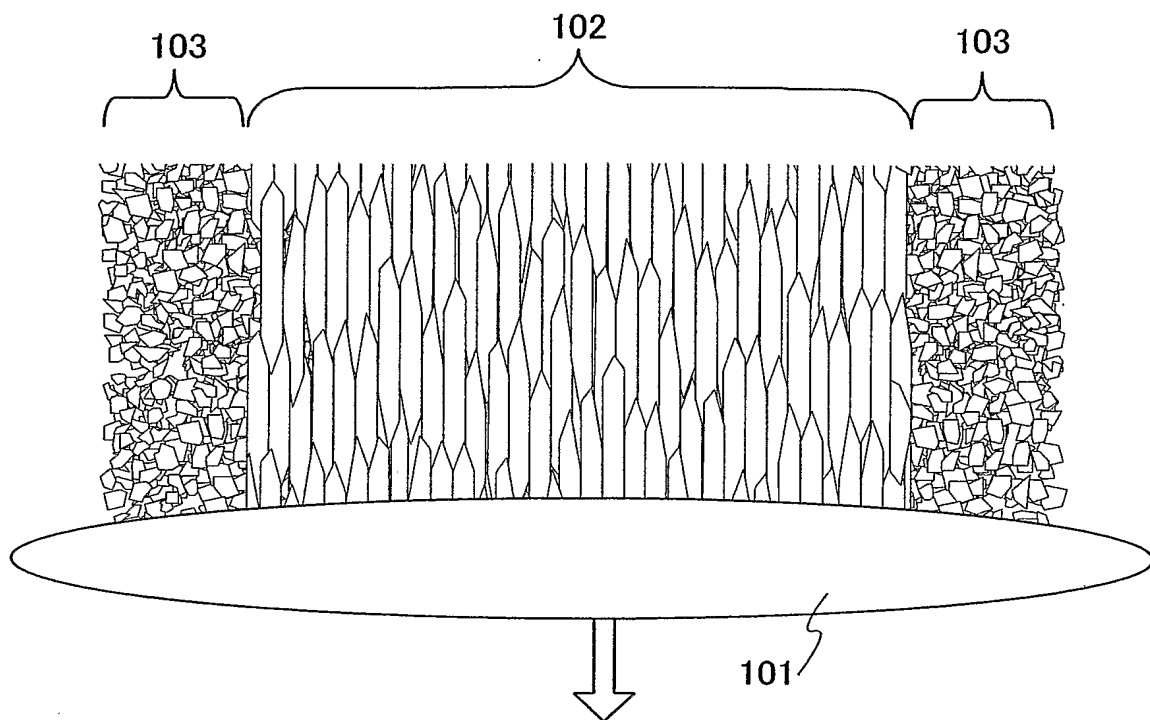


FIG. 1B

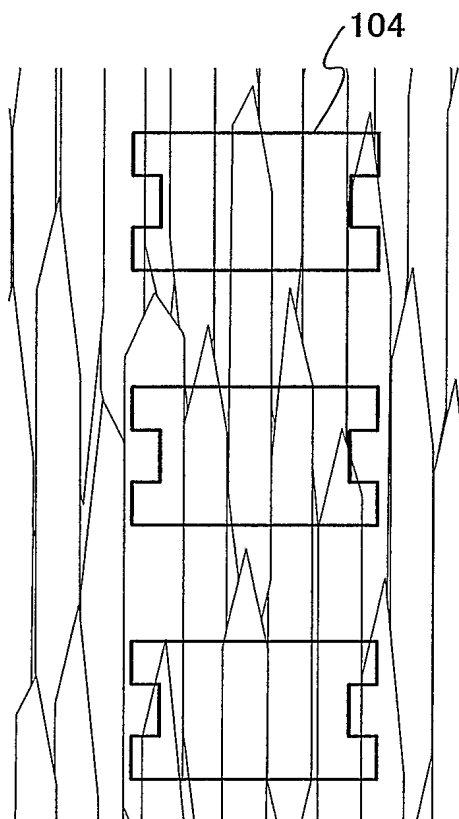
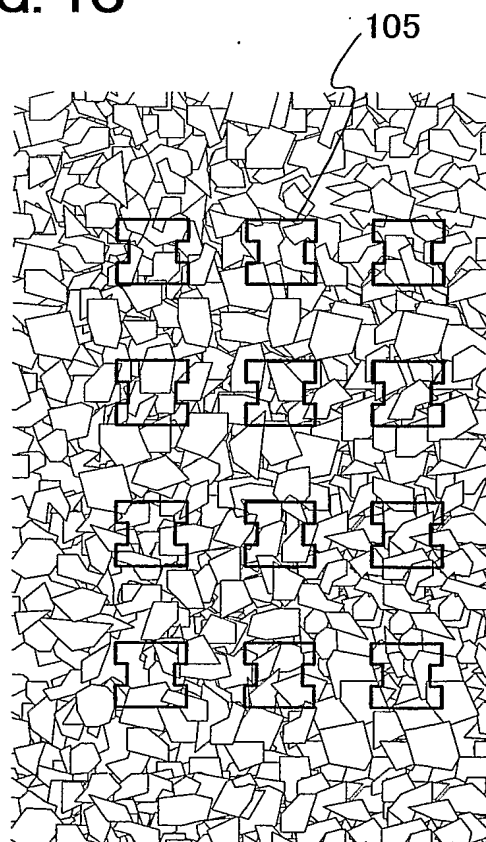


FIG. 1C



2/23

FIG. 2A

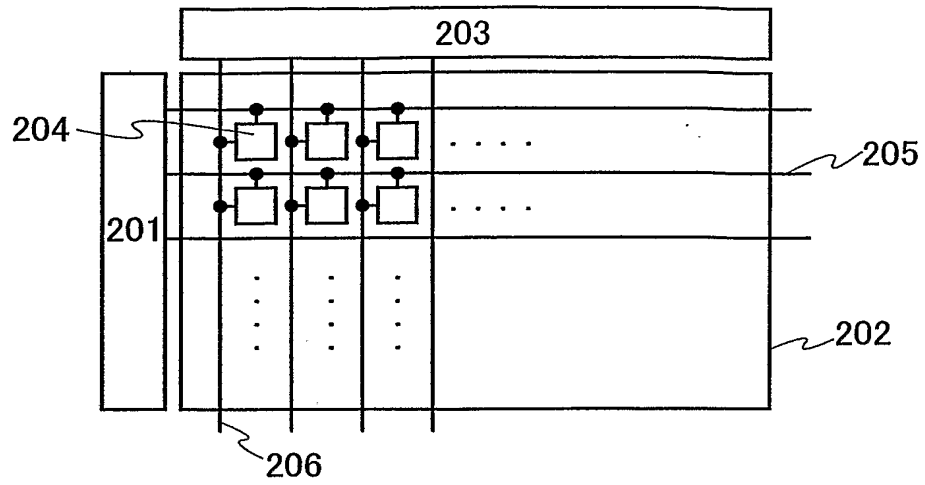


FIG. 2B

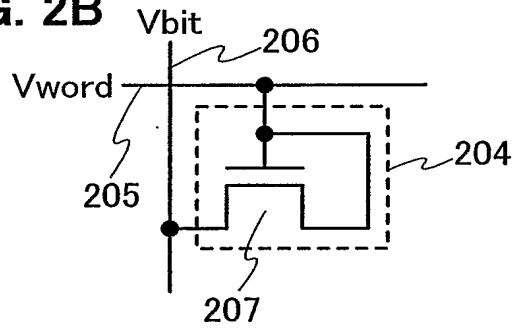
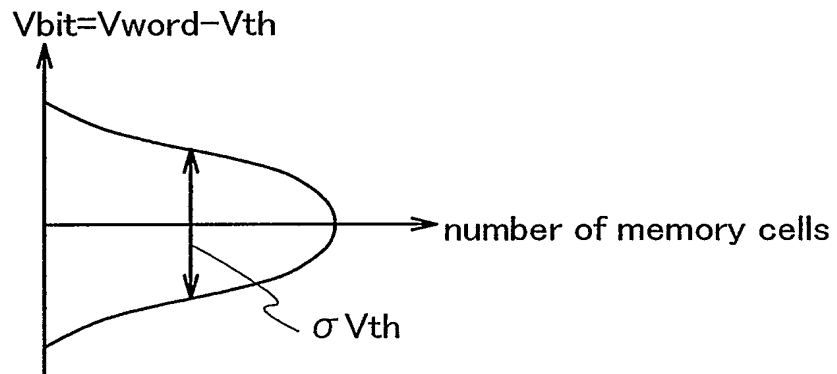
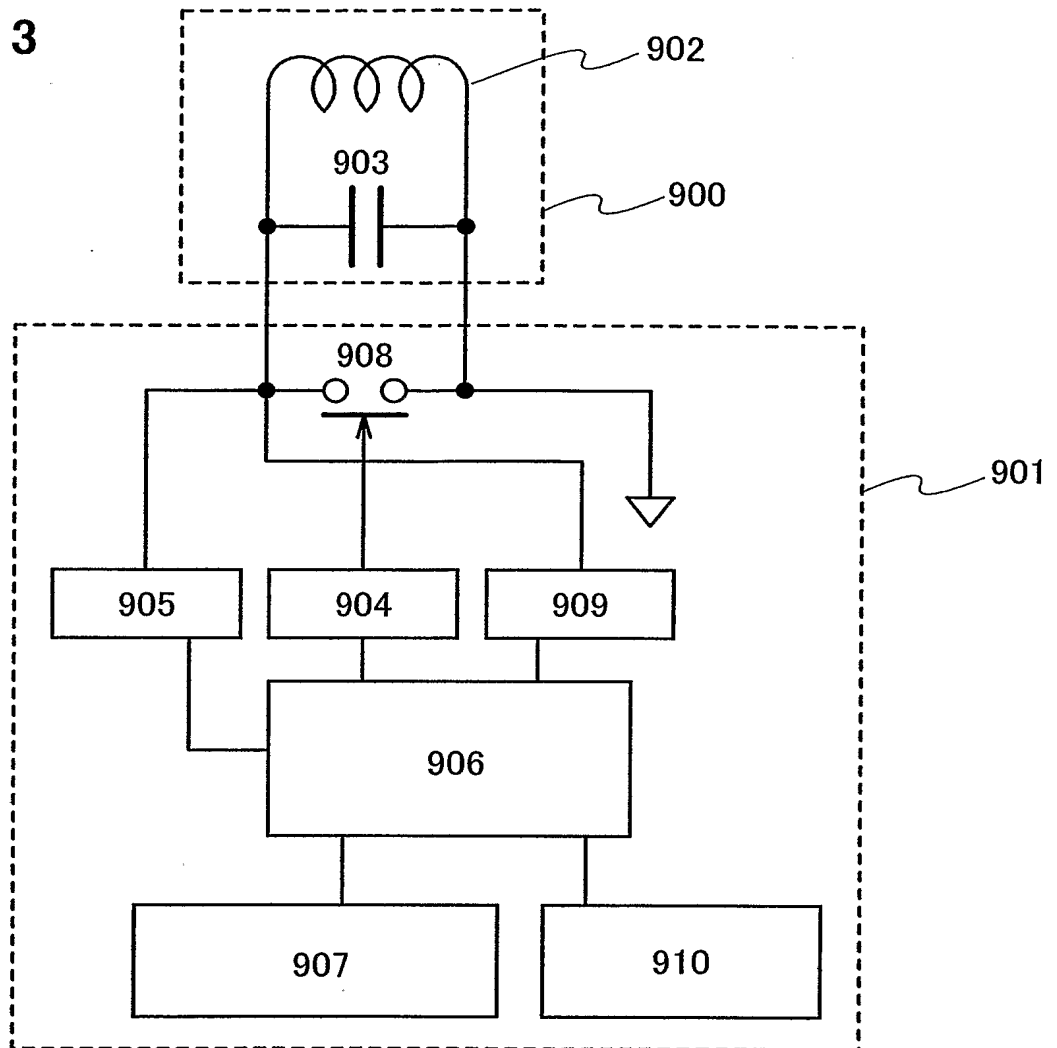


FIG. 2C



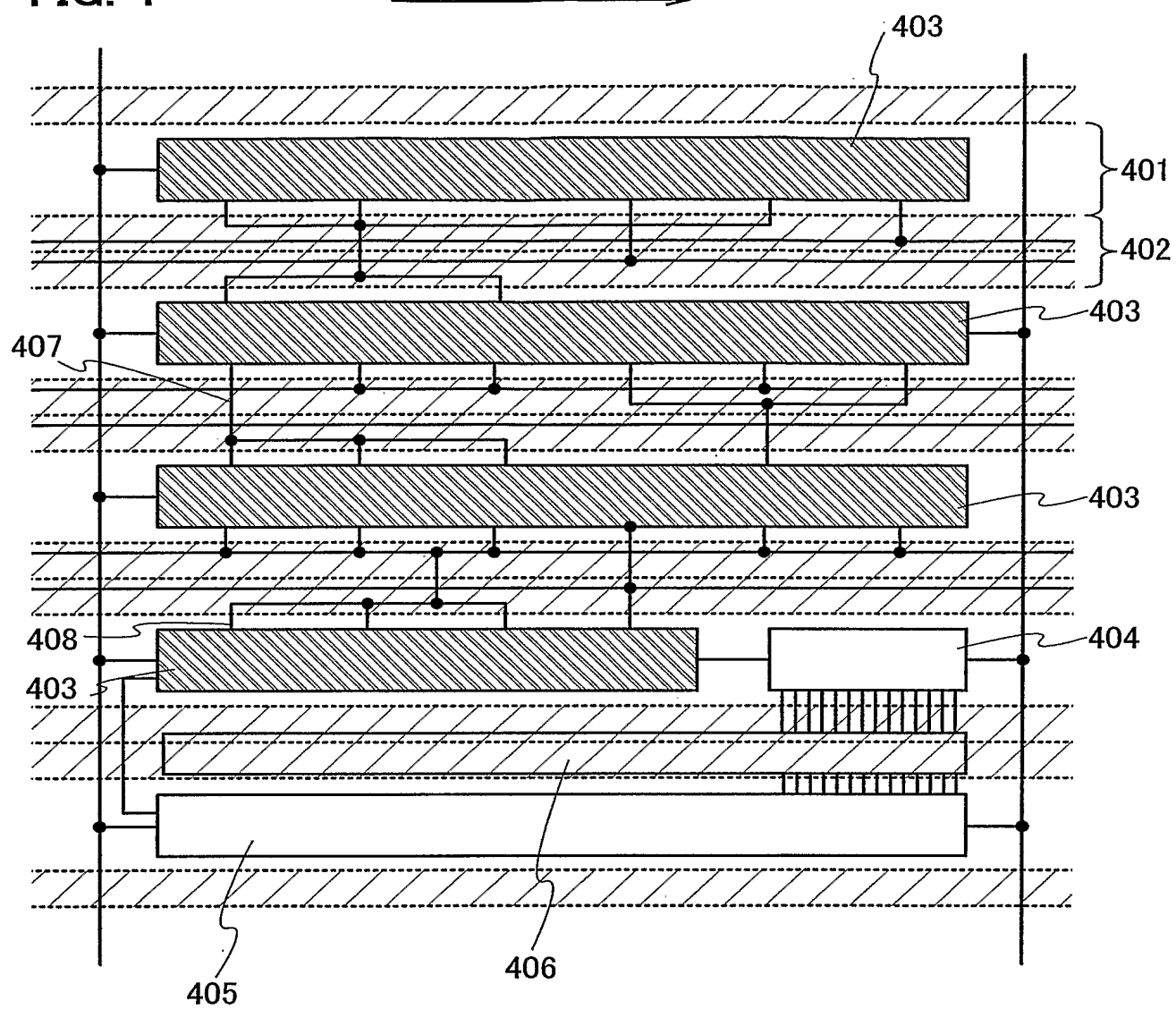
3/23

FIG. 3



4/23

FIG. 4



5/23

FIG. 5A

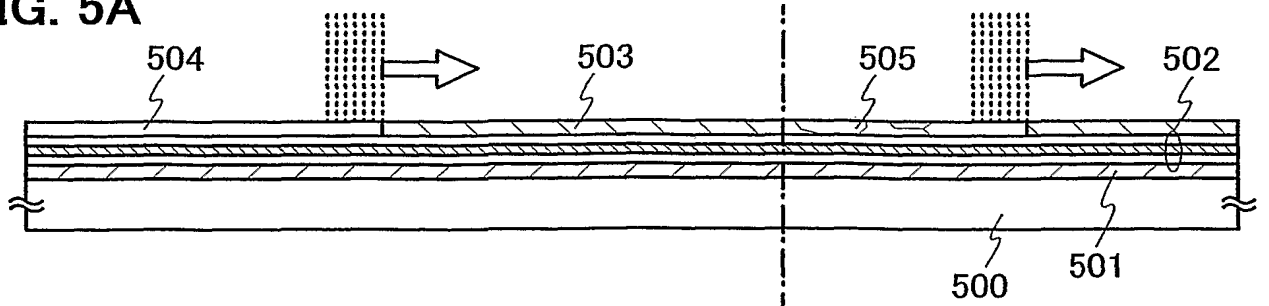


FIG. 5B

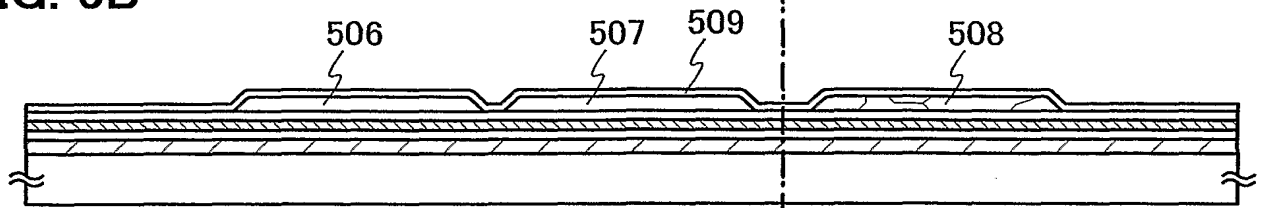


FIG. 5C

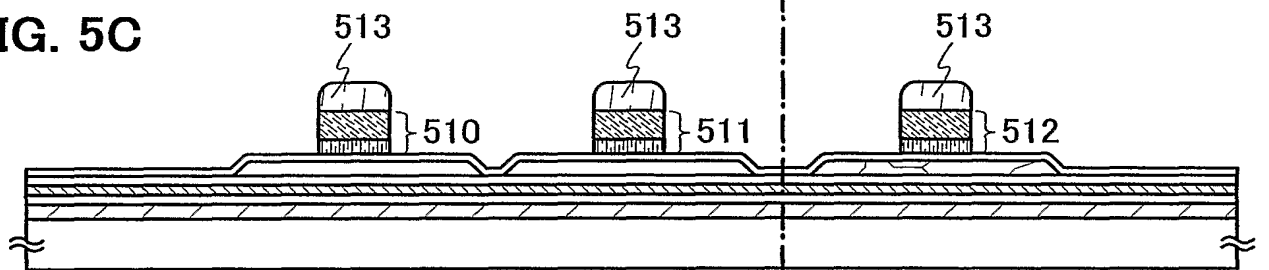


FIG. 5D

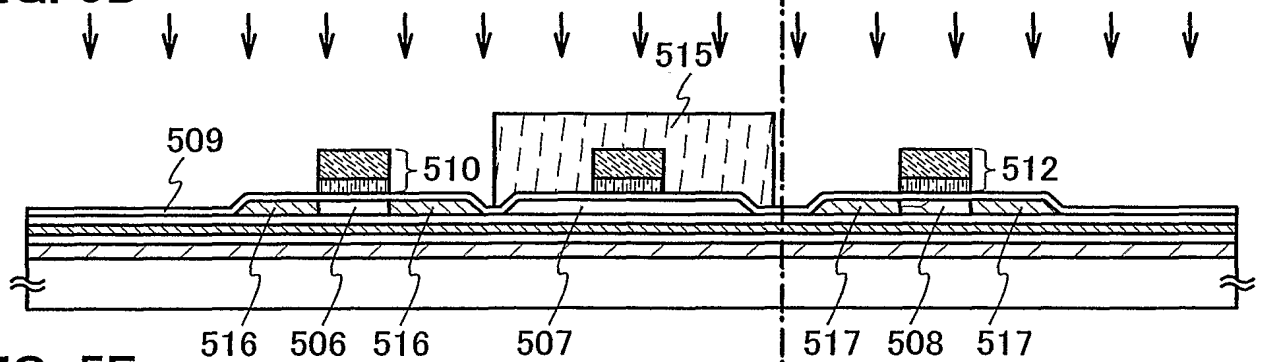
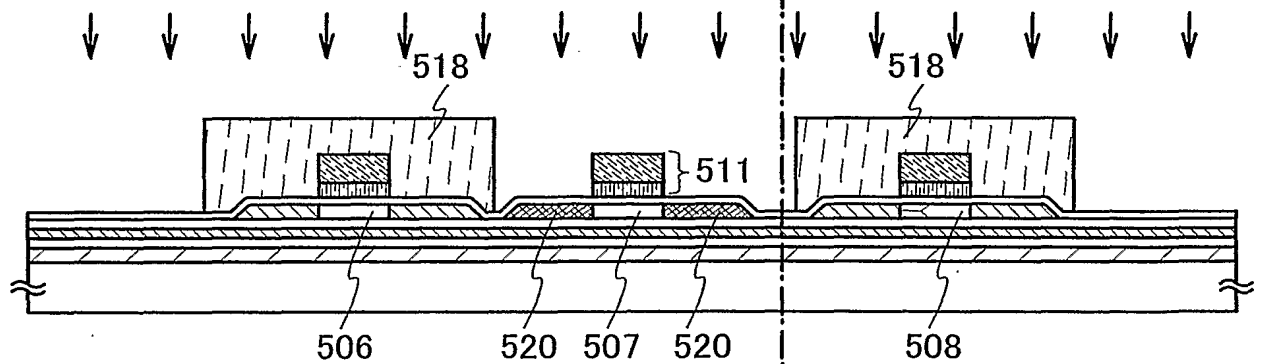


FIG. 5E



6/23

FIG. 6A

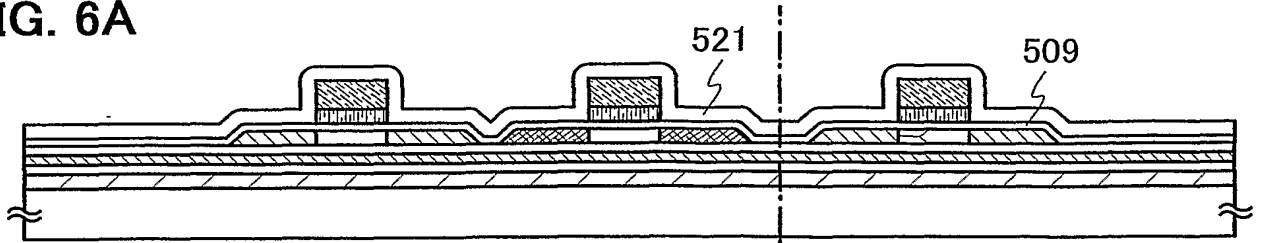


FIG. 6B

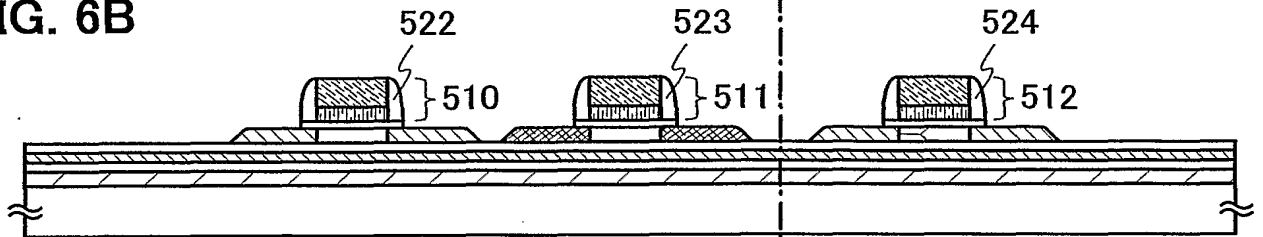


FIG. 6C

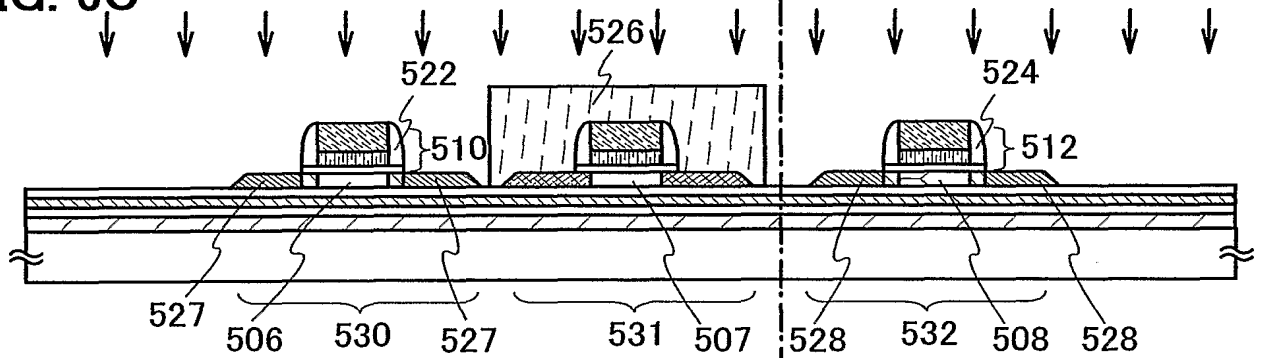


FIG. 6D

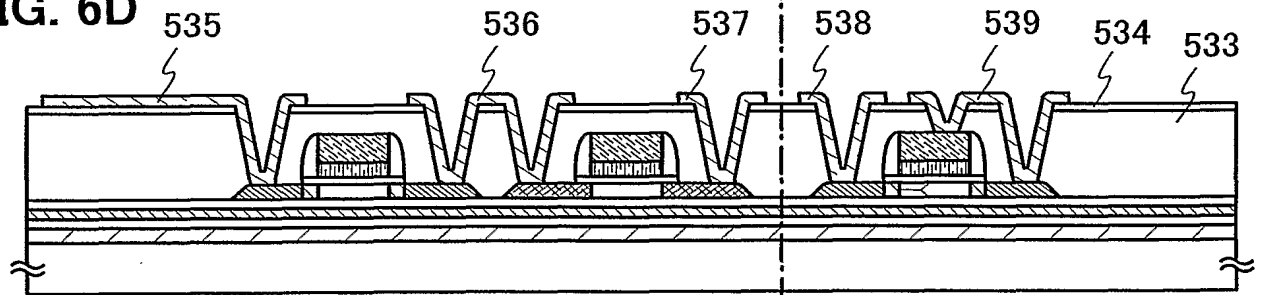
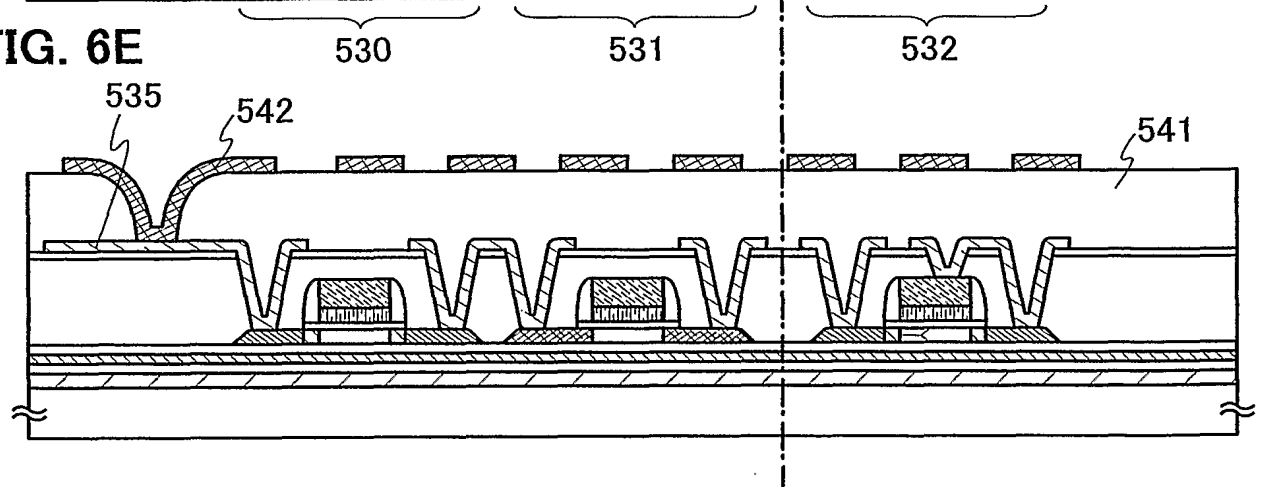


FIG. 6E



7/23

FIG. 7A

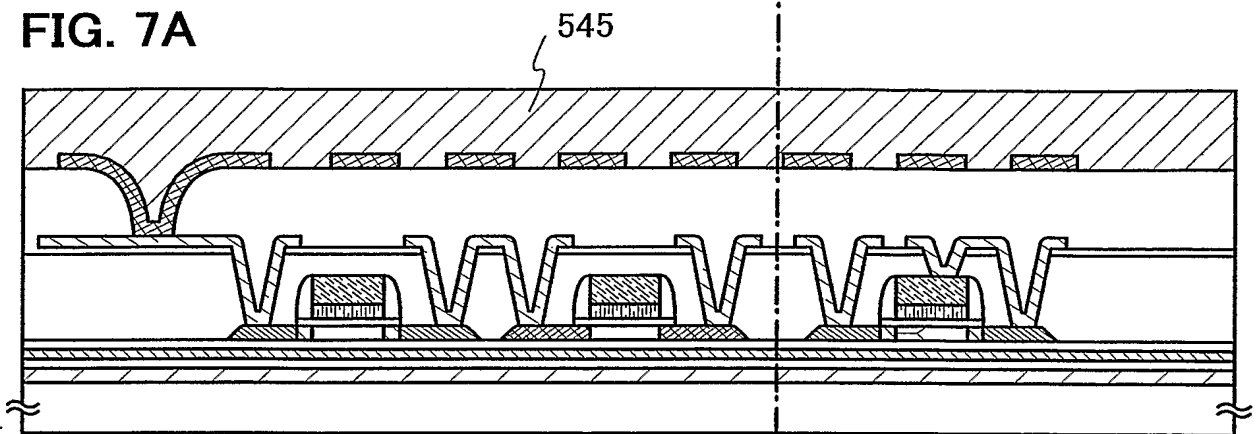


FIG. 7B

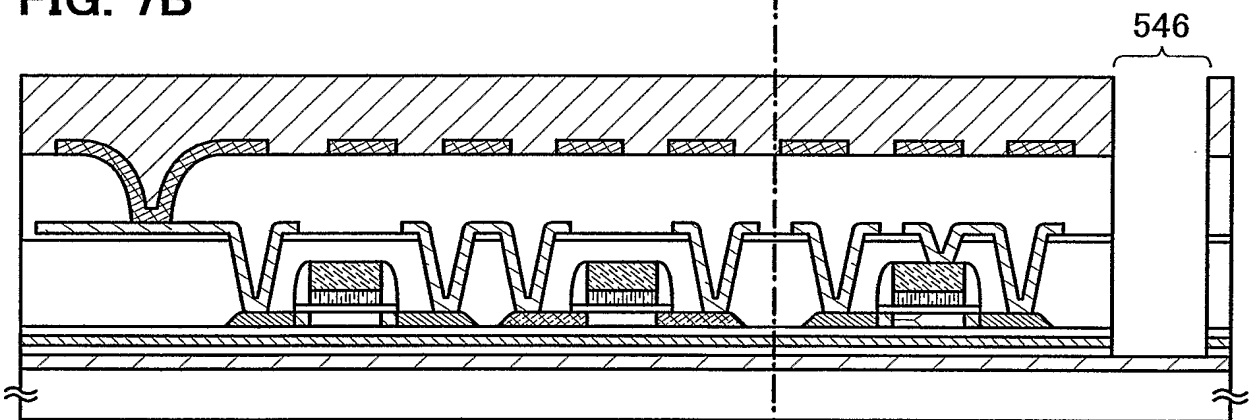
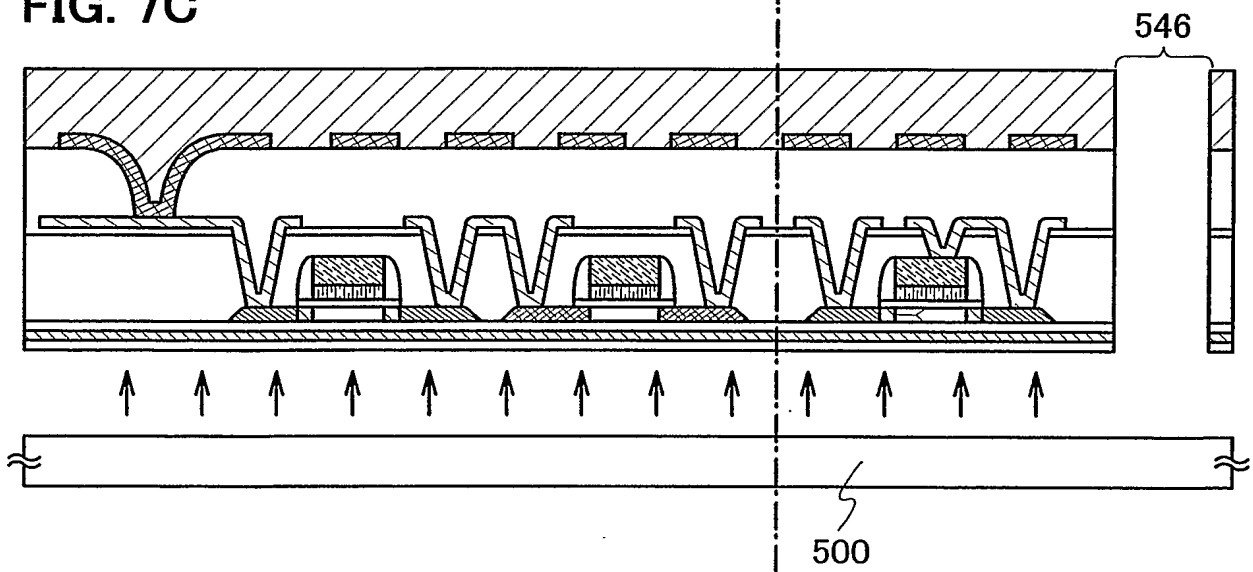


FIG. 7C



8/23

FIG. 8A

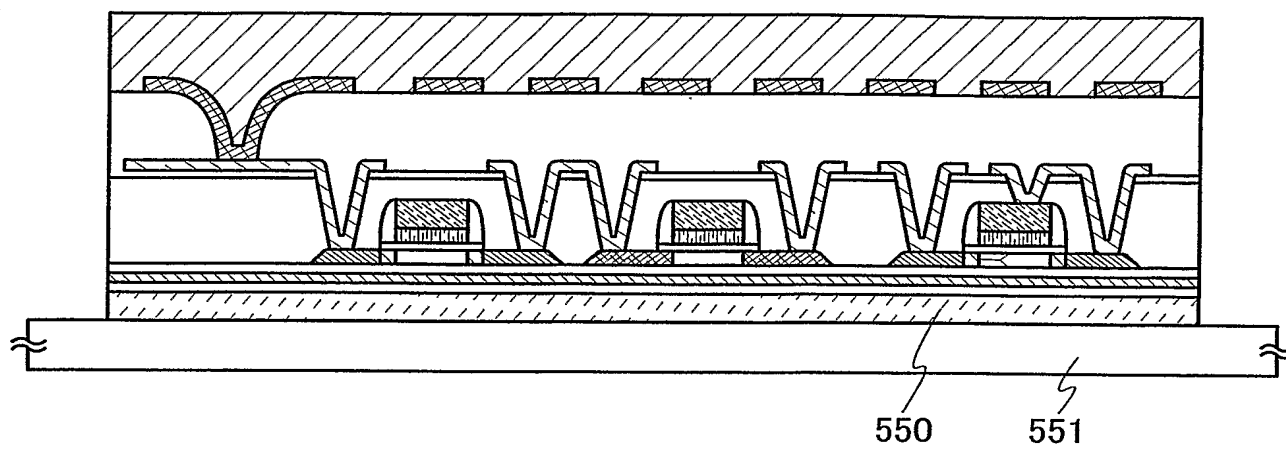
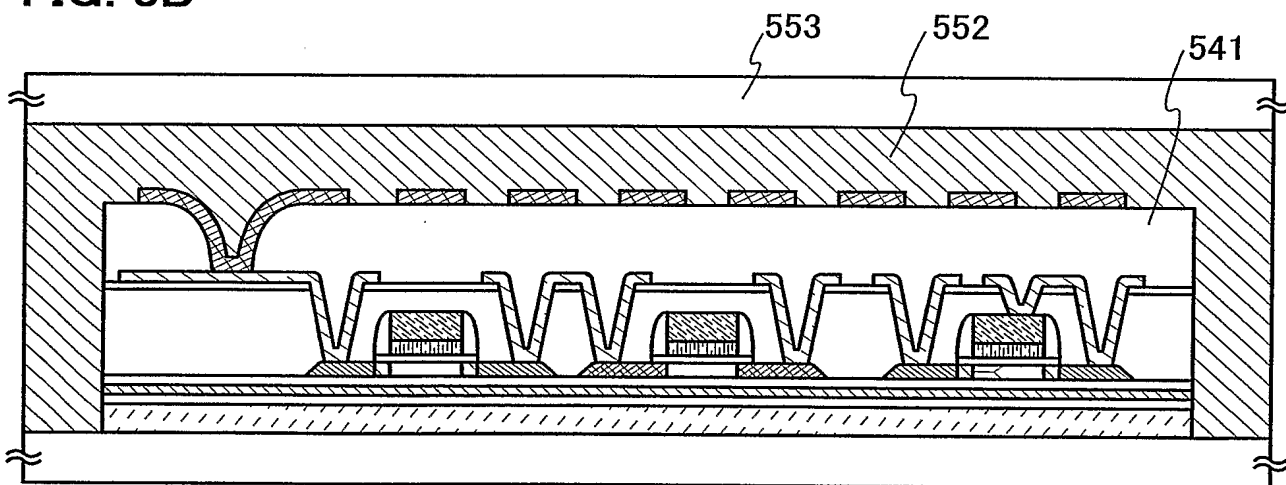
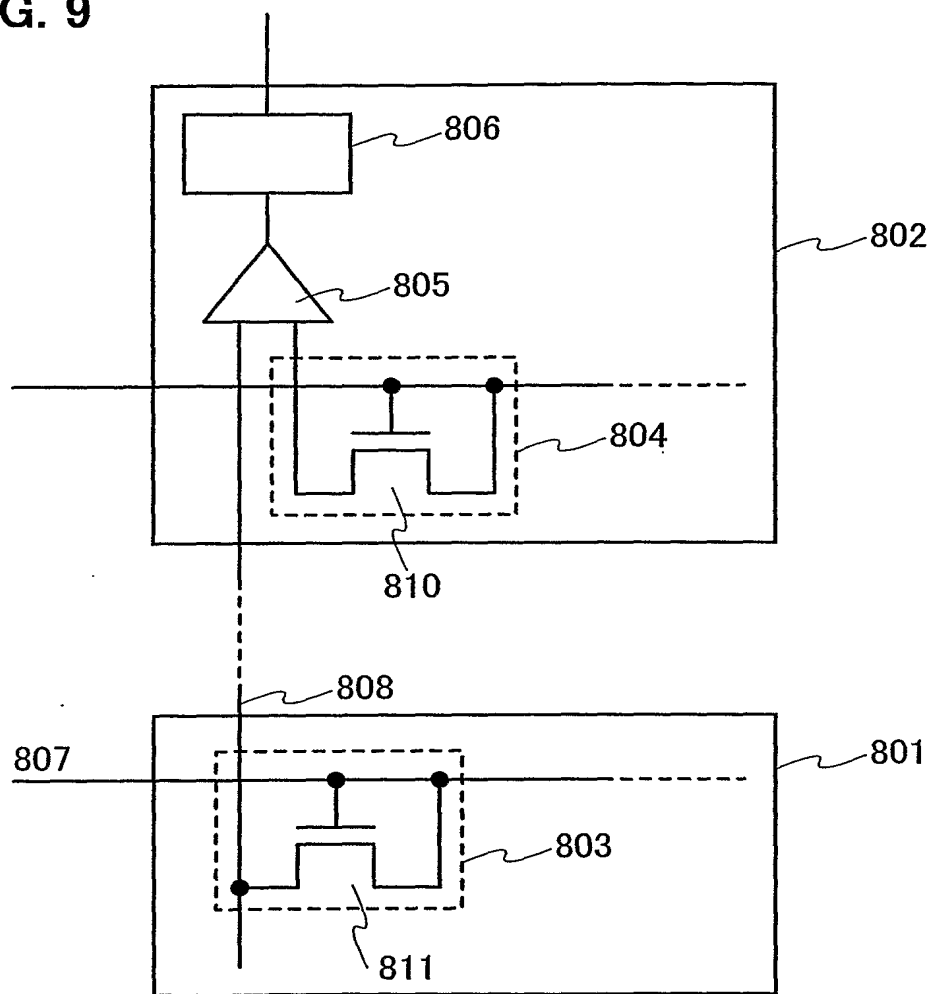


FIG. 8B



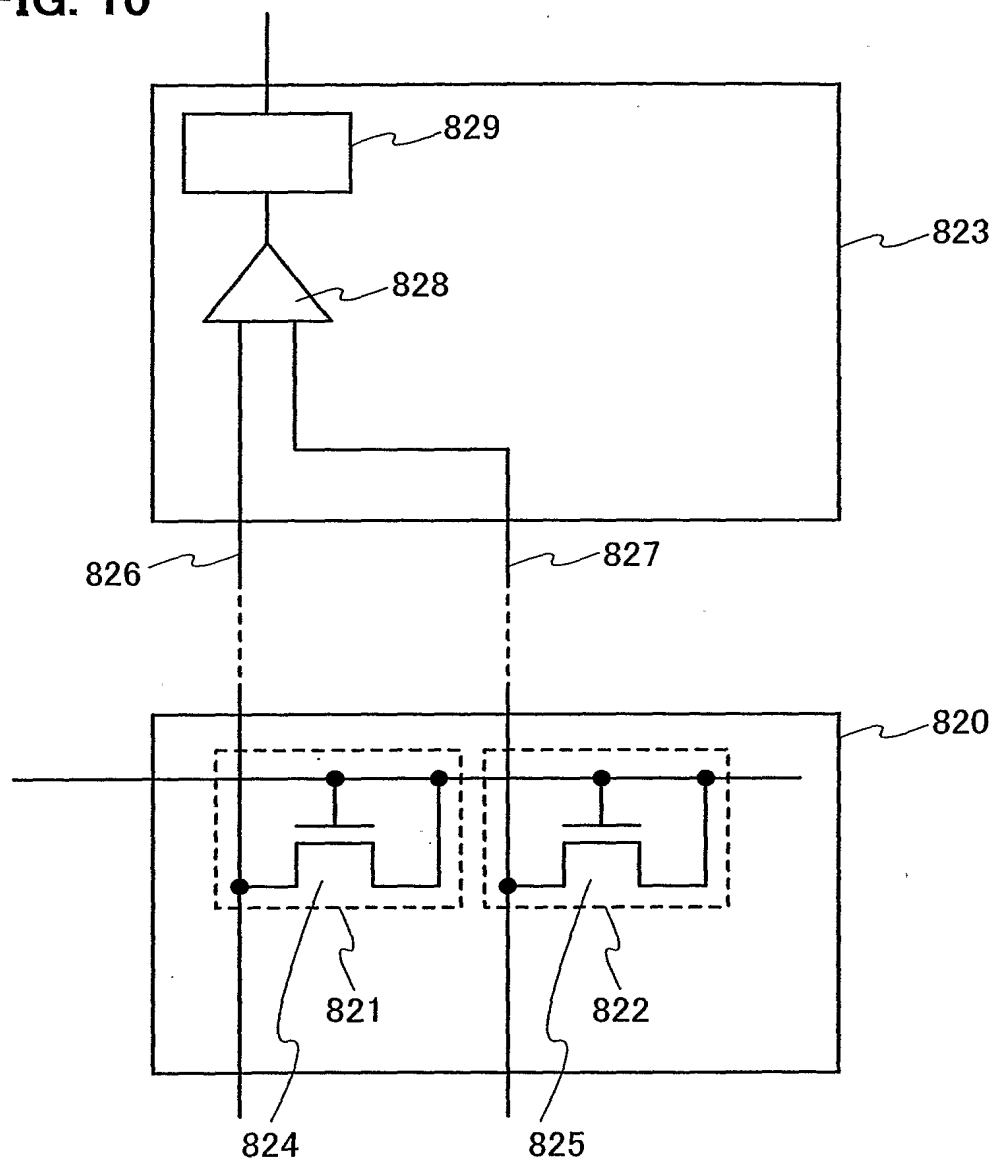
9/23

FIG. 9



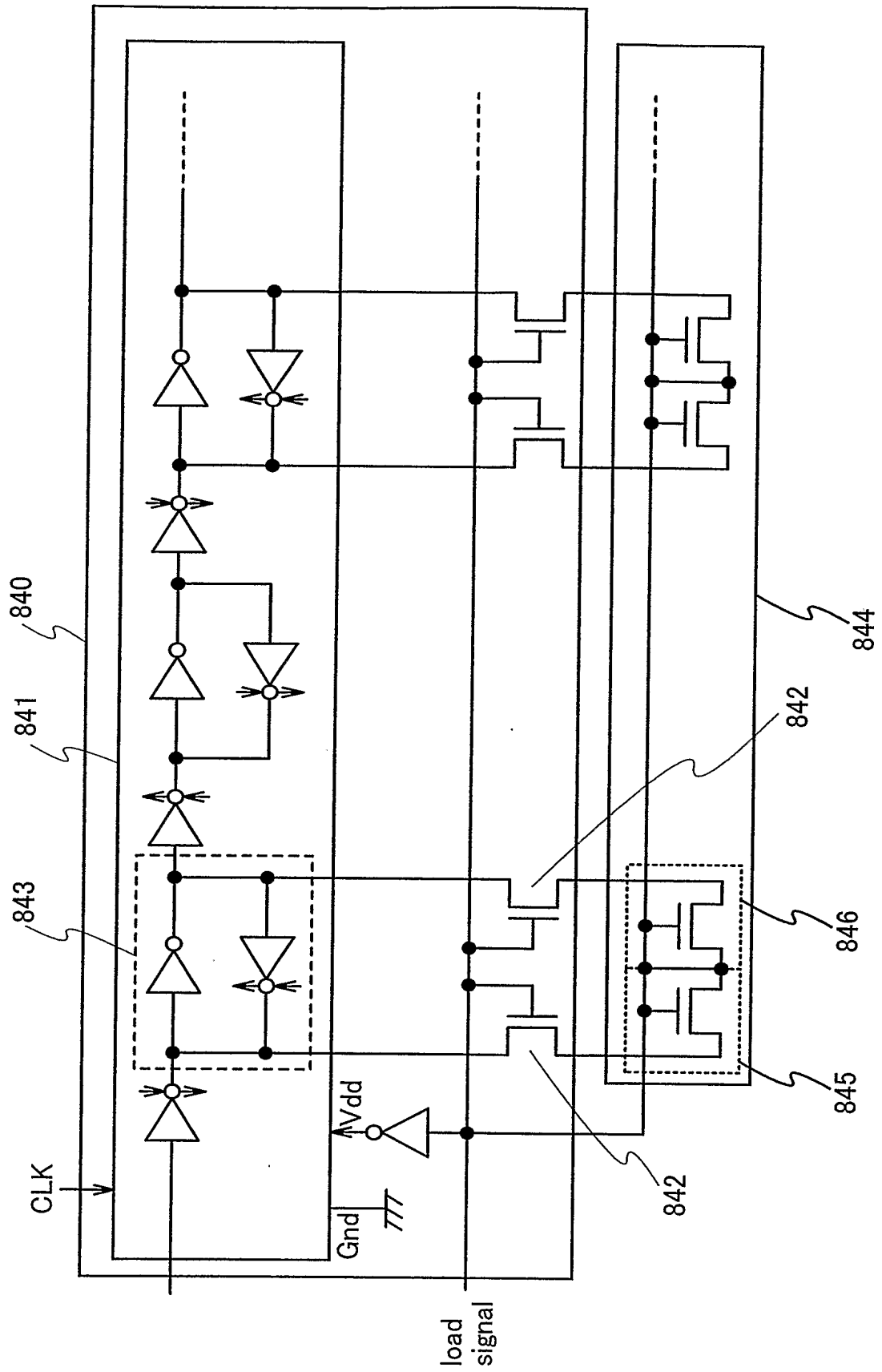
10/23

FIG. 10



11/23

FIG. 11



12/23

FIG. 12A

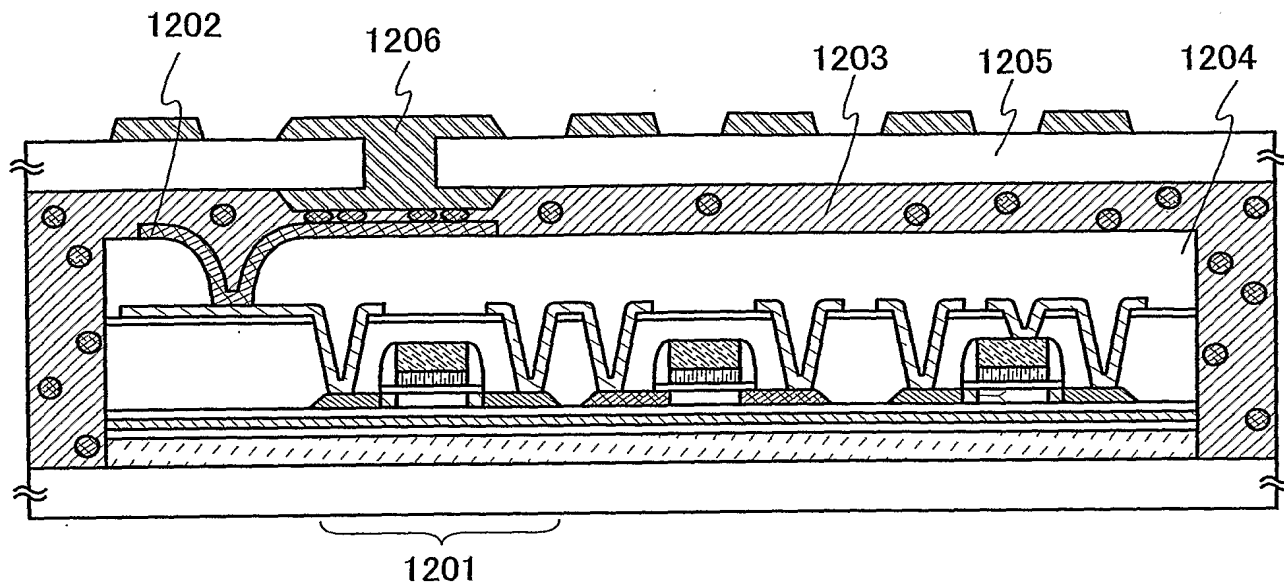
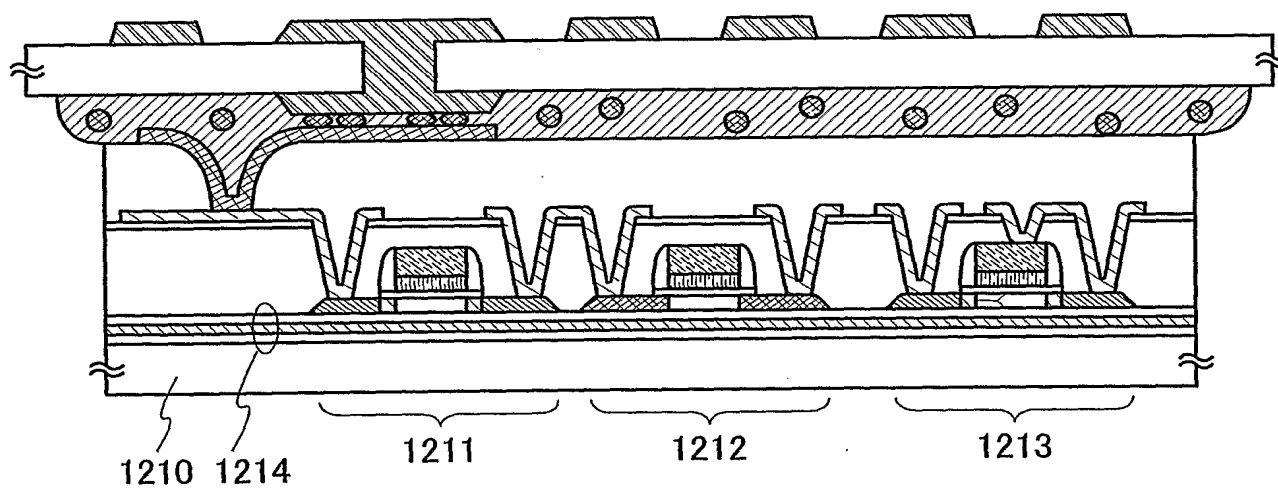


FIG. 12B



13/23

FIG. 13A

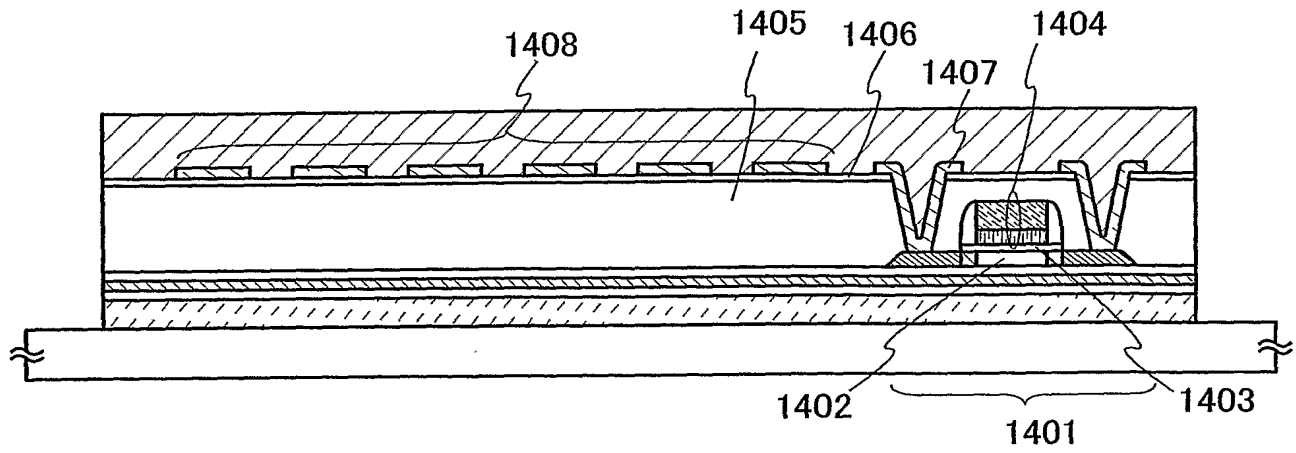
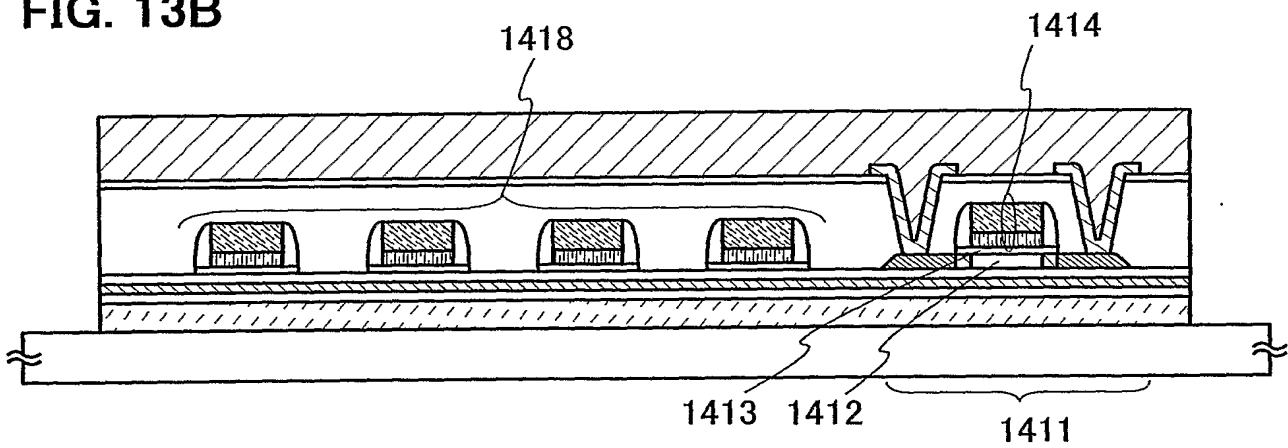


FIG. 13B



14/23

FIG. 14A

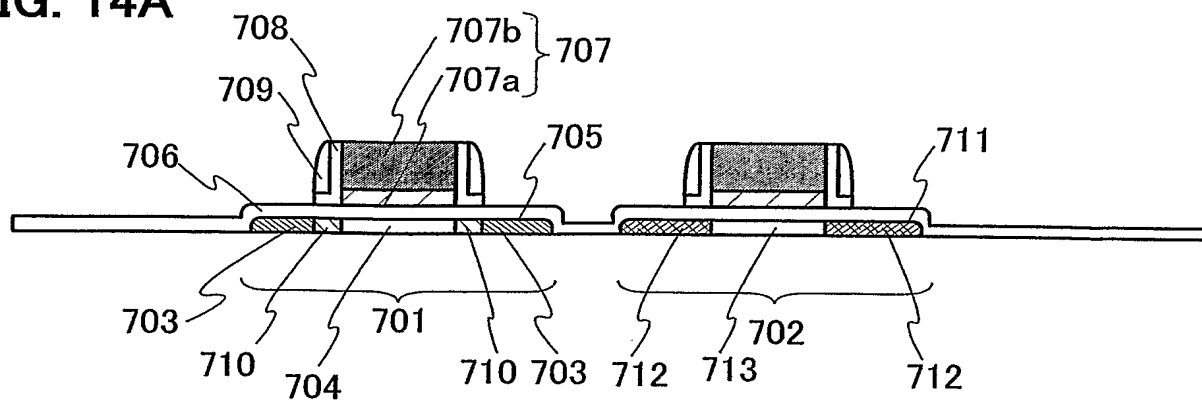


FIG. 14B

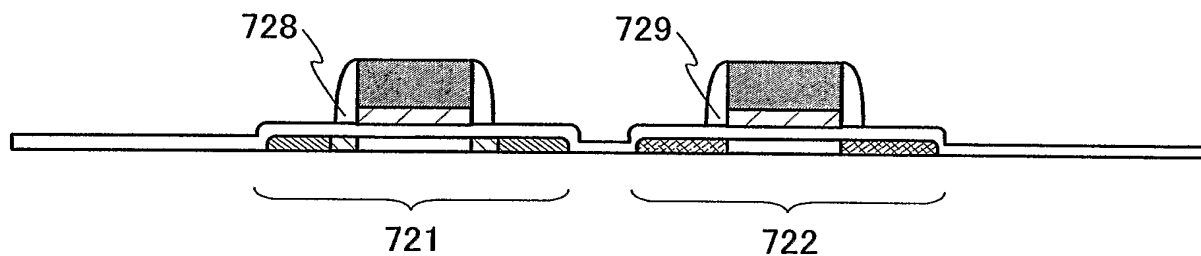
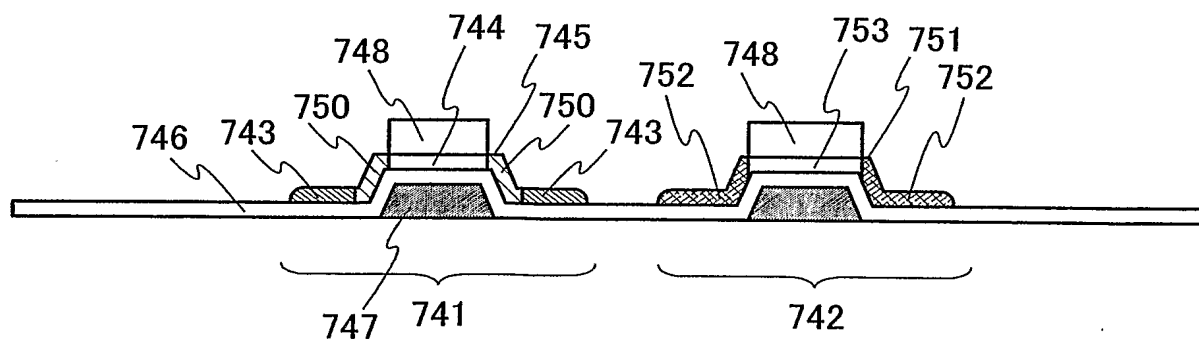


FIG. 14C



15/23

FIG. 15A

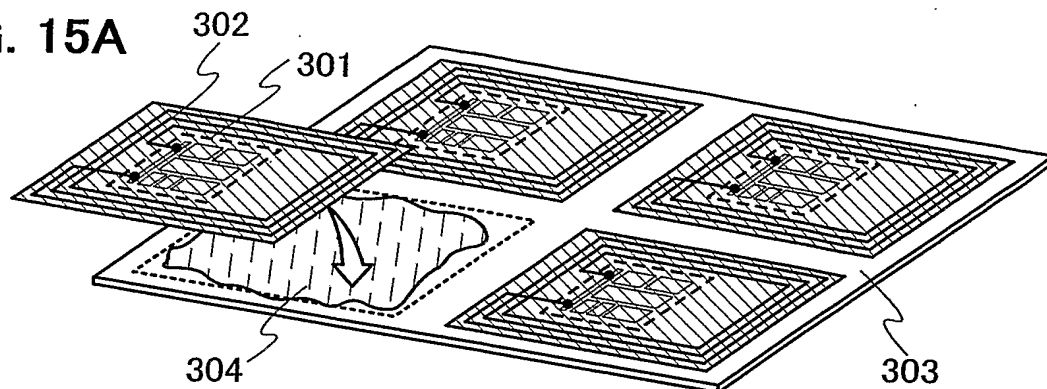


FIG. 15B

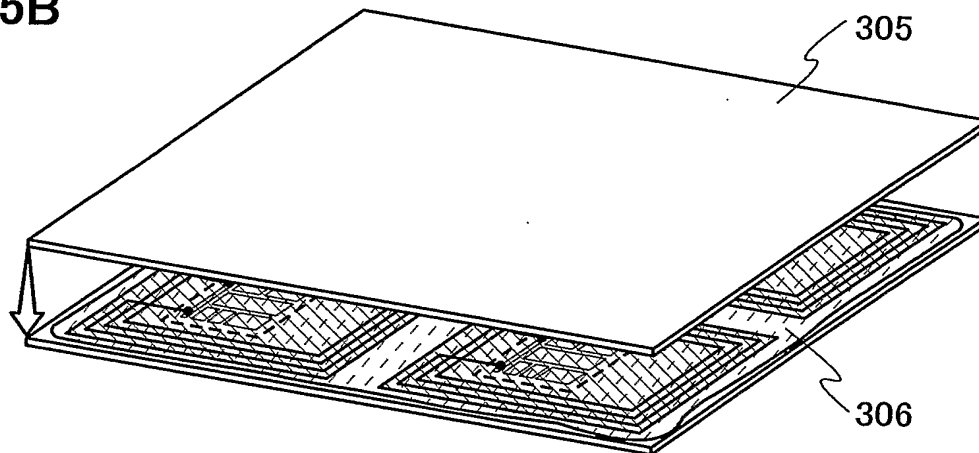


FIG. 15C

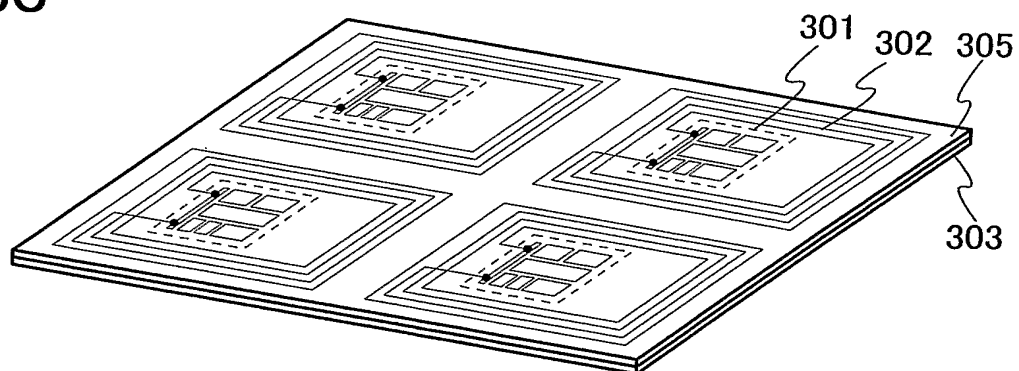
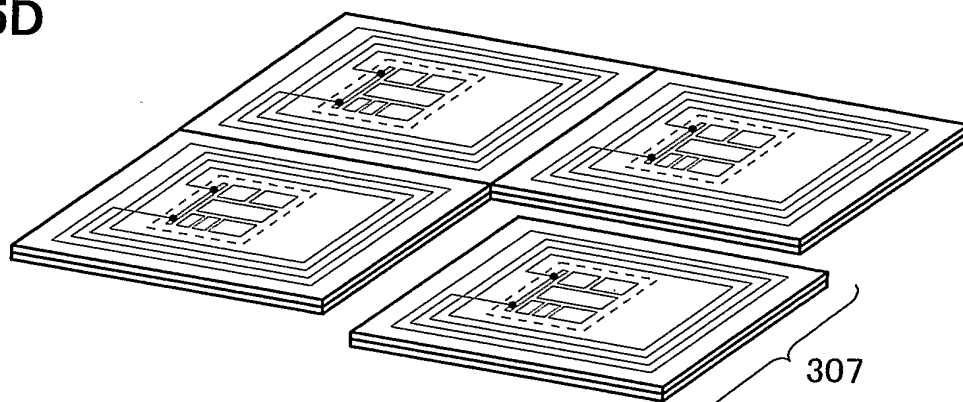


FIG. 15D



16/23

FIG. 16A

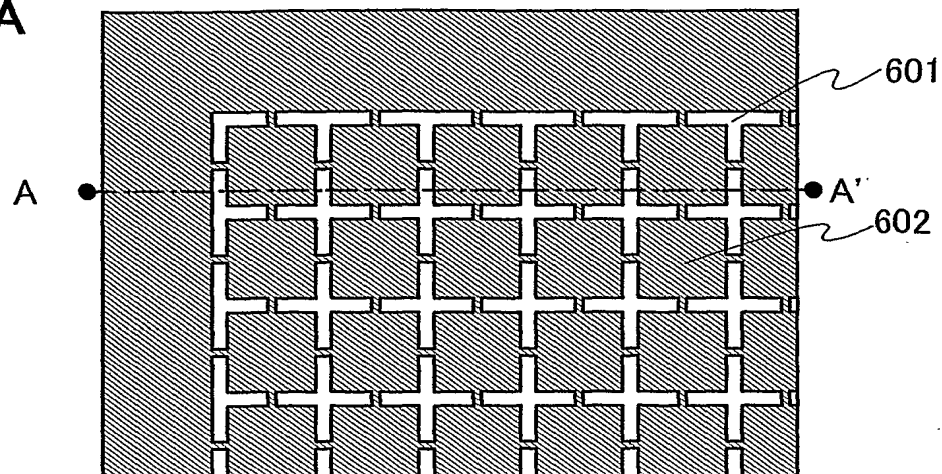


FIG. 16B

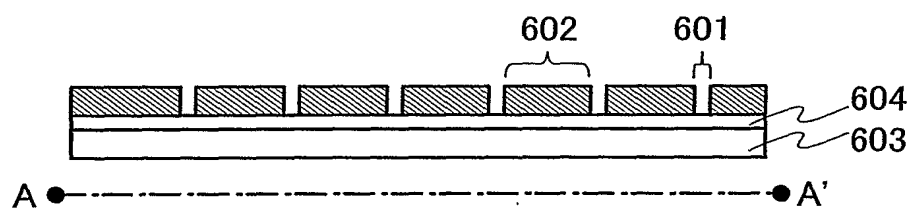


FIG. 16C

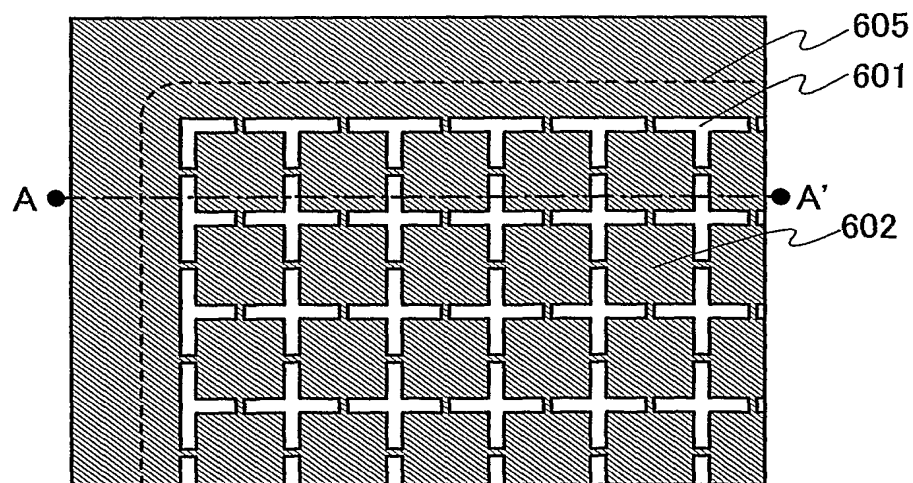
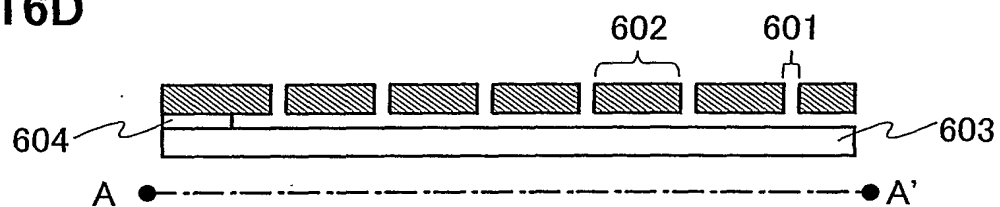


FIG. 16D



17/23

FIG. 17A

CHECK

Place ○○○○○○○○○○
○○Bank○○Blanch

Amount **¥1,234,567**※

Date YYYY/MM/DD
○○○○○INC.

Place ○○ President ○○

Stamp

1301

1302

FIG. 17B

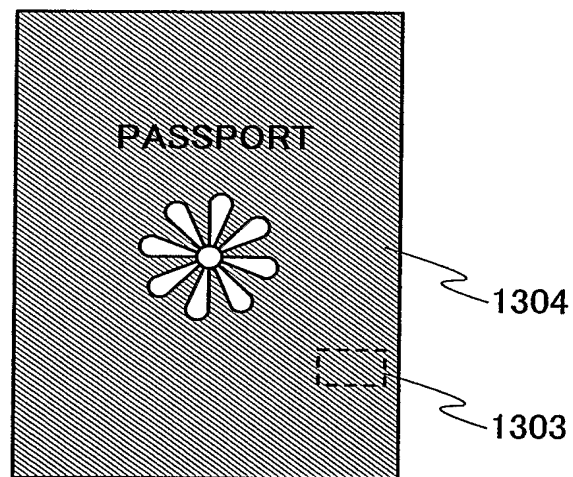
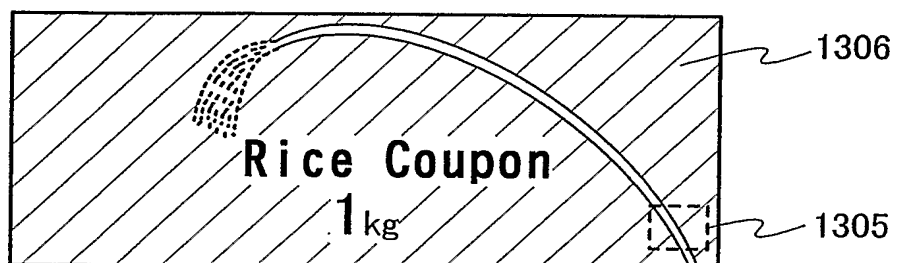


FIG. 17C



18/23

FIG. 18A

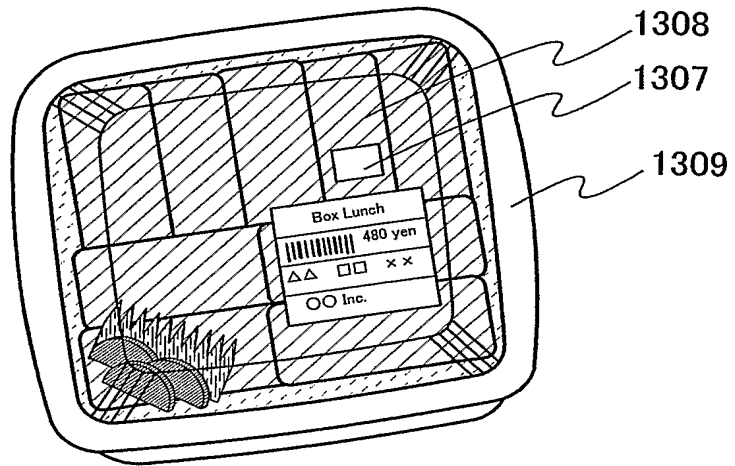


FIG. 18B

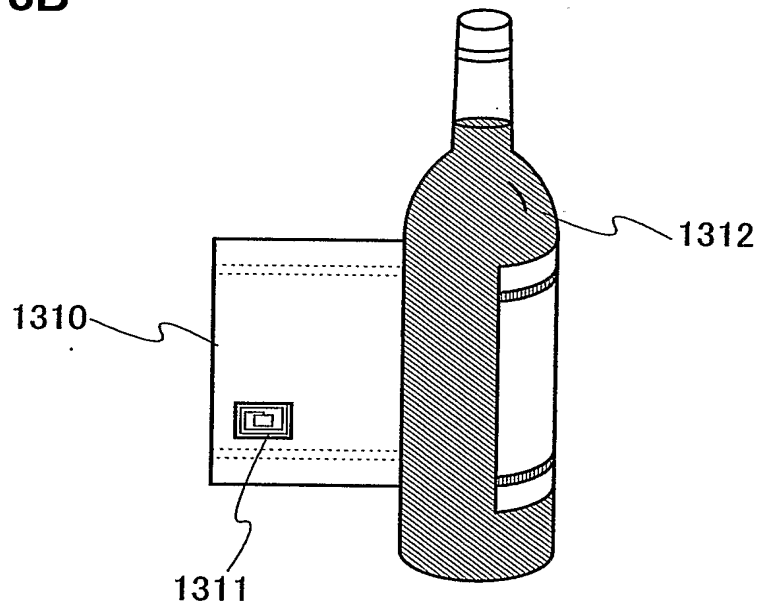
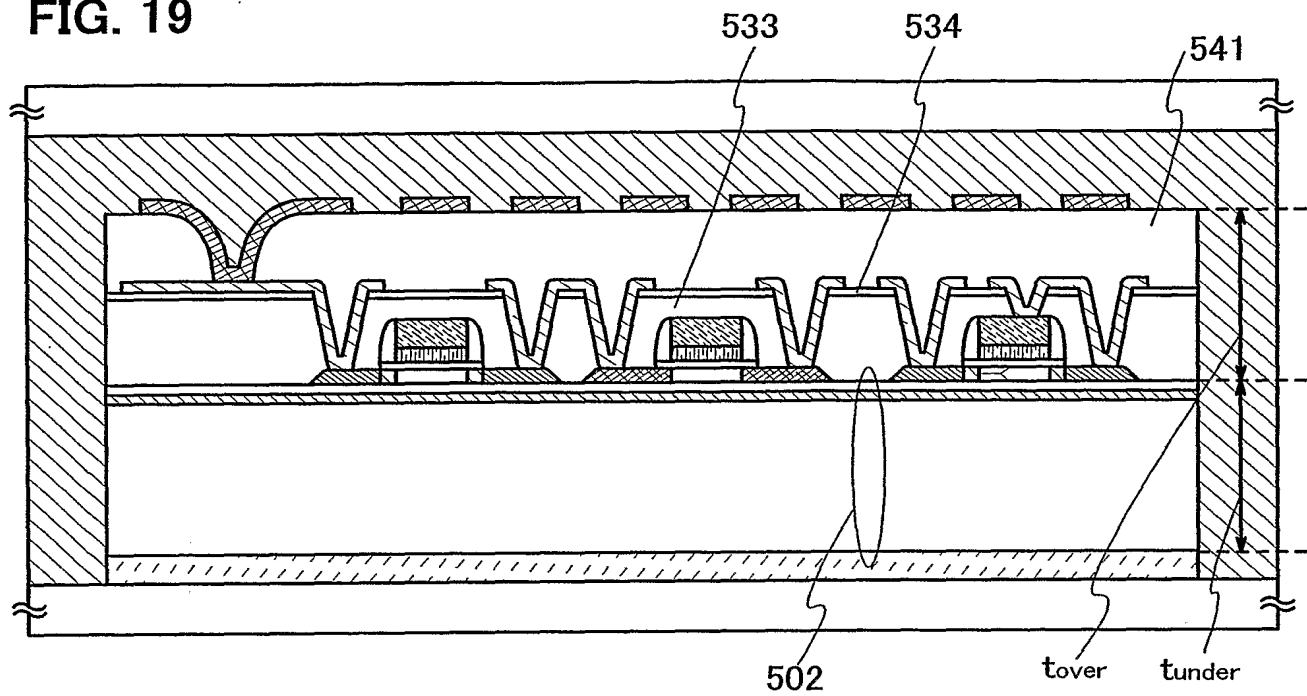


FIG. 19



20/23

FIG. 20A

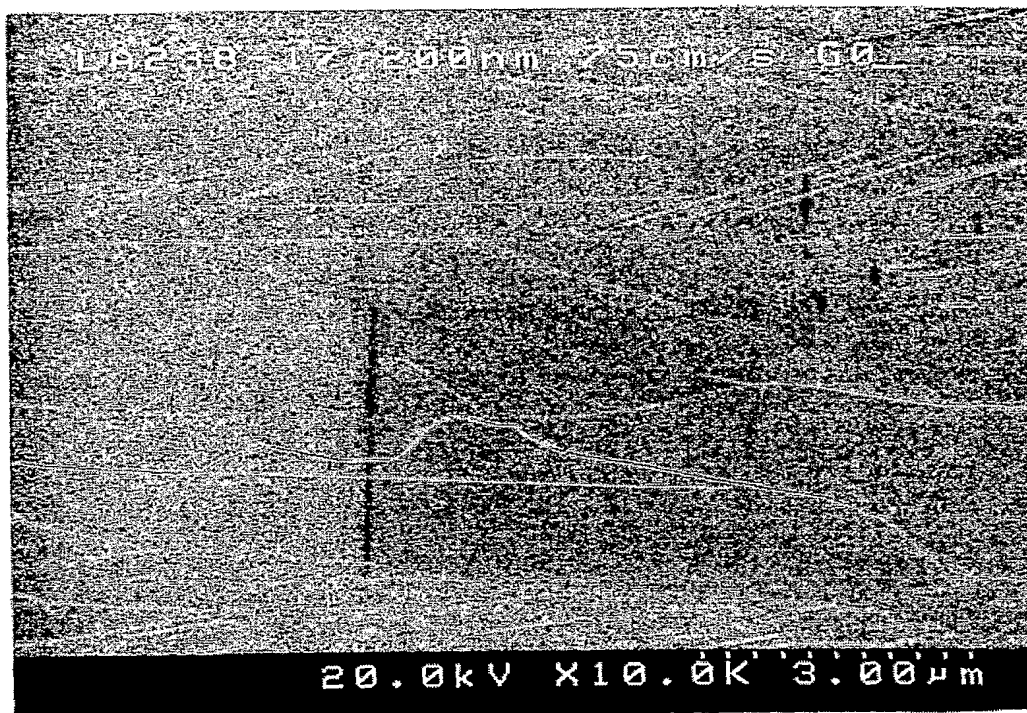
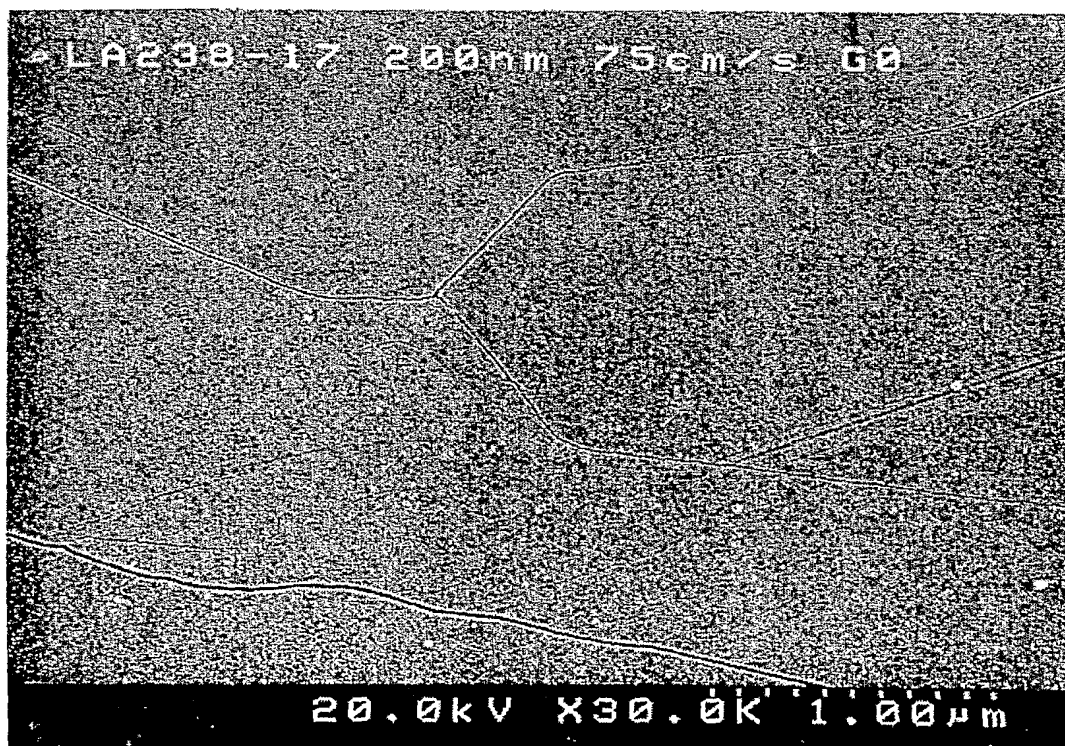
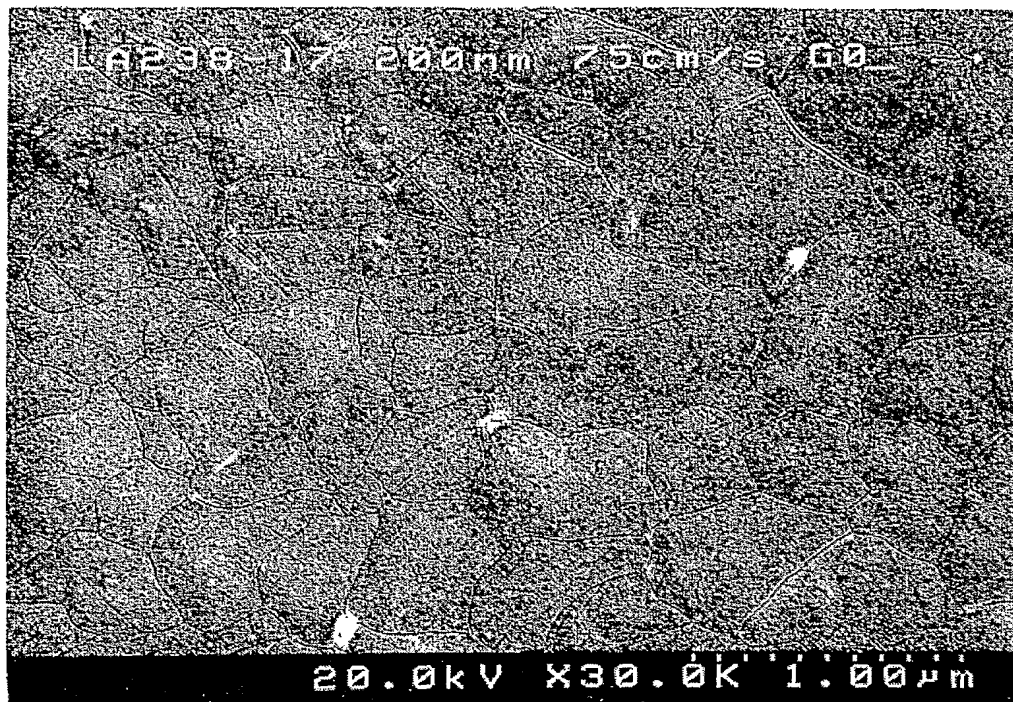


FIG. 20B



21/23

FIG. 21



EXPLANATION OF REFERENCE

101: BEAM SPOT, 102: REGION, 103: REGION, 104: ACTIVE LAYER, 105:
ACTIVE LAYER, 201: DECODER, 202: MEMORY CELL ARRAY, 203: CIRCUIT,
204: MEMORY CELL, 205: WORD LINE, 206: BIT LINE, 207: TFT, 301:
5 INTEGRATED CIRCUIT, 302: ANTENNA, 303: SUBSTRATE, 304: ADHESIVE
AGENT, 305: COVER MEMBER, 306: ADHESIVE AGENT, 307: ID CHIP, 401:
REGION, 402: REGION, 403: CIRCUIT, 404: CIRCUIT, 405: DECODER, 406:
MEMORY CELL ARRAY, 500: SUBSTRATE, 501: STRIPPING LAYER, 502: BASE
FILM, 503: SEMICONDUCTOR FILM, 504: REGION, 505: REGION, 506:
10 SEMICONDUCTOR FILM, 507: SEMICONDUCTOR FILM, 508:
SEMICONDUCTOR FILM, 509: GATE INSULATING FILM, 510: GATE
ELECTRODE, 511: GATE ELECTRODE, 512: GATE ELECTRODE, 513: RESIST,
515: RESIST, 516: LOW-DENSITY IMPURITY REGION, 518: RESIST, 520:
HIGH-DENSITY IMPURITY REGION, 521: INSULATING FILM, 522: SIDE WALL,
15 526: RESIST, 527: HIGH-DENSITY IMPURITY REGION, 528: HIGH-DENSITY
IMPURITY REGION, 530: N-CHANNEL TFT, 531: P-CHANNEL TFT, 532:
N-CHANNEL TFT, 533: INTERLAYER INSULATING FILM, 534: INTERLAYER
INSULATING FILM, 535: WIRING, 536: WIRING, 538: WIRING, 539: WIRING, 541:
INTERLAYER INSULATING FILM, 542: ANTENNA, 545: PROTECTIVE LAYER,
20 546: GROOVE, 550: ADHESIVE AGENT, 551: SUBSTRATE, 552: ADHESIVE
AGENT, 553: COVER MEMBER, 601: GROOVE, 602: INTEGRATED CIRCUIT,
603: SUBSTRATE, 604: STRIPPING LAYER, 605: DOTTED LINE, 701:
N-CHANNEL TFT, 702: P-CHANNEL TFT, 703: IMPURITY REGION, 704:
CHANNEL-FORMING REGION, 705: SEMICONDUCTOR FILM, 706: GATE
25 INSULATING FILM, 707: GATE ELECTRODE, 707a: CONDUCTIVE FILM, 707b:
CONDUCTIVE FILM, 708: SIDEWALL, 709: SIDEWALL, 710: LDD (LIGHTLY
DOPED DRAIN) REGION, 711: SEMICONDUCTOR FILM, 712: IMPURITY
REGION, 713: CHANNEL-FORMING REGION, 721: N-CHANNEL TFT, 722:
P-CHANNEL TFT, 728: SIDEWALL, 741: N-CHANNEL TFT, 742: P-CHANNEL
30 TFT, 743: IMPURITY REGION, 744: CHANNEL-FORMING REGION, 745:

23/23

SEMICONDUCTOR FILM, 746: GATE INSULATING FILM, 747: GATE ELECTRODE, 748: PROTECTIVE FILM, 750: LDD (LIGHTLY DOPED DRAIN) REGION, 751: SEMICONDUCTOR FILM, 752: IMPURITY REGION, 753: CHANNEL-FORMING REGION, 801: MEMORY CELL ARRAY, 802: CIRCUIT, 5 803: MEMORY CELL, 804: REFERENCE MEMORY CELL, 805: DIFFERENTIAL AMPLIFIER CIRCUIT, 806: LATCH CIRCUIT, 807: WORD LINE, 808: BIT LINE, 810: TFT, 811: TFT, 820: MEMORY CELL ARRAY, 821: MEMORY CELL, 823: CIRCUIT, 824: TFT, 826: BIT LINE, 828: DIFFERENTIAL AMPLIFIER CIRCUIT, 829: LATCH CIRCUIT, 840: CIRCUIT, 841: SHIFT REGISTER, 842: SWITCHING 10 ELEMENT, 843: FLIP-FLOP CIRCUIT, 844: MEMORY CELL ARRAY, 845: MEMORY CELL, 900: ANTENNA, 901: INTEGRATED CIRCUIT, 902: ANTENNA COIL, 903: CAPACITOR ELEMENT, 904: MODULATOR CIRCUIT, 905: RECTIFIER CIRCUIT, 906: MICROPROCESSOR, 907: MEMORY, 908: SWITCH, 909: DEMODULATOR CIRCUIT, 910: RANDOM ROM, 1201: TFT, 1202: WIRING, 15 1203: ADHESIVE AGENT, 1204: INTERLAYER INSULATING FILM, 1205: COVER MEMBER, 1206: ANTENNA, 1210: SUBSTRATE, 1211: TFT, 1214: BASE FILM, 1301: CHECK, 1302: ID CHIP, 1303: ID CHIP, 1304: PASS PORT, 1305: ID CHIP, 1306: MERCHANDISE COUPON, 1307: ID CHIP, 1308: PACKAGING MATERIAL, 1309: LUNCH BOX, 1310: LABEL, 1311: ID CHIP, 1312: PRODUCT, 20 1401: TFT, 1402: SEMICONDUCTOR FILM, 1403: GATE INSULATING FILM, 1404: GATE ELECTRODE, 1405: INTERLAYER INSULATING FILM, 1406: INTERLAYER INSULATING FILM, 1407: WIRING, 1408: ANTENNA, 1411: TFT, 1412: SEMICONDUCTOR FILM, 1413: GATE INSULATING FILM, 1414: GATE ELECTRODE, and 1418: ANTENNA.